CMOSIC FROM 64K byte, RAM 2048 byte on-chip

8-bit 1-chip Microcontroller



http://onsemi.com

Overview

The LC87F6D64A is 8-bit microcomputer with the following on-chip functional blocks:

- CPU: operable at a minimum bus cycle time of 100ns
- 64K-byte flash ROM (re-writeable on board/On-chip debugger)
- On-chip RAM: 2048 byte
- VFD automatic display controller/driver
- 16-bit timer/counter (can be divided into two 8-bit timers)
- two 8-bit timer with prescaler
- timer for use as date/time clock
- Day-Minute-Second Counter (DMSC)
- System clock divider function
- Synchronous serial I/O port (with automatic block transmit /receive function)
- Asynchronous/synchronous serial I/O port
- Remote control receive function
- 8-channel×8-bit AD converter
- 14-source 10-vectored interrupt system

All of the above functions are fabricated on a single chip.

Features

- ■Flash ROM
 - Single 5V power supply, writeable on-board.
 - Block erase in 128 byte units
 - 65536×8 bits

\blacksquare RAM

• 2048×9 bits

* This product is licensed from Silicon Storage Technology, Inc. (USA).

■Minimum Bus Cycle Time

- 100ns (10MHz) V_{DD}=3.0 to 5.5V
- 150ns (4MHz) V_{DD}=2.5 to 5.5V

Note: The bus cycle time indicates ROM read time.

- ■Minimum Instruction Cycle Time (tCYC)
 - 300ns (10MHz) V_{DD}=3.0 to 5.5V
 - 750ns (4MHz) V_{DD}=2.5 to 5.5V

■Ports

• Input/output ports

Data direction programmable for each bit individually: 10 (P1n, P7n)
Data direction programmable in nibble units: 8 (P0n)

(When N-channel open drain output is selected, data can be input in bit units.)

• VFD output ports

Large current outputs for digits: 9 (S0/T0 to S8/T8)

Large current outputs for digits/segments: 7 (S9/T9 to S15/T15)

Digit/segment outputs: 8 (S16 to S23)

Segment outputs: 30 (S24 to S53)

• Oscillator pins: 2 (CF1/XT1, CF2/XT2)

• Reset pin: 1 (RES)

• Power supply: 4 (VSS1, VDD1 to VDD3)

• VFD power supply: 1 (VP)

■VFD Automatic Display Controller

Programmable segment/digit output pattern
 Output can be switched between digit/segment waveform output (pins 9 to 23 can be used for output of digit waveforms).
 parallel-drive available for large current VFD.

• 16-step dimmer function available

■Timers

• Timer 0: 16-bit timer/counter with capture register

Mode 0: 2 channel 8-bit timer with programmable 8-bit prescaler and 8-bit capture register

Mode 1: 8-bit timer with 8-bit programmable prescaler and 8-bit capture register

+ 8-bit counter with 8-bit capture register

Mode 2: 16-bit timer with 8-bit programmable prescaler and 16-bit capture register

Mode 3: 16-bit counter with 16-bit capture register

- Timer 4: 8-bit timer with 6-bit prescaler
- Timer 5: 8-bit timer with 6-bit prescaler
- Base Timer
 - 1) The clock signal can be selected from any of the following.

Sub-clock (32.768kHz crystal oscillator), system clock, and prescaler output from timer 0

- 2) Interrupts can be selected to occur at one of five different times.
- Day and time counter
 - 1) Using with a base timer, it can be used as 65000 day + minute + second counter.

■SIO

- SIO 0: 8-bit synchronous serial interface
 - 1) LSB first /MSB first function available
 - 2) Internal 8-bit baud-rate generator (maximum transmit clock period 4/3 tCYC)
 - 3) Consecutive automatic data communication
 - (1 to 256 bits (communication available for each bit) (stop and reopening available for each byte))
- SIO 1: 8-bit asynchronous/synchronous serial interface
 - Mode 0: Synchronous 8-bit serial IO (2-wire or 3-wire, transmit clock 2 to 512 tCYC)
 - Mode 1: Asynchronous serial IO (half duplex, 8 data bits, 1 stop bit, baud rate 8 to 2048 tCYC)
 - Mode 2: Bus mode 1 (start bit, 8 data bits, transmit clock 2 to 512 tCYC)
 - Mode 3: Bus mode 2 (start detection, 8 data bits, stop detection)

■AD Converter: 8 bits × 8 channels

- ■Remote Control Receiver Circuit (sharing pins with P70/INT0/RMIN)
 - Noise rejection function
 - (Units of noise rejection filter: about 120µs, when selecting a 32.768kHz crystal oscillator as a clock.)
 - Supporting reception formats with a guide-pulse of half-clock/clock/none.
 - Determines a end of reception by detecting a no-signal periods (No carrier). (Supports same reception format with a different bit length.)
 - X'tal HOLD mode release function

■Watchdog Timer

- The watching timer period is set using an external RC.
- Watchdog timer can produce interrupt, system reset.

■Clock Output Function

- 1) Able to output selected oscillation clock 1/1, 1/2, 1/4, 1/8, 1/16, 1/32, or 1/64 as system clock.
- 2) Able to output oscillation clock of sub clock.
- ■Interrupts: 14 sources, 10 vector interrupts
 - Three priority (low, high and highest) multiple interrupts are supported. During interrupt handling, an equal or lower priority interrupt request is refused.
 - If interrupt requests to two or more vector addresses occur at once, the higher priority interrupt takes precedence. In the case of equal priority levels, the vector with the lowest address takes precedence.

No.	Vector	Selectable Level	Interrupt Signal
1	00003H	X or L	INT0
2	0000BH	X or L	INT1
3	00013H	H or L	INT2/T0L/remote control receiver
4	0001BH	H or L	INT3/Base timer 0/1
5	00023H	H or L	тон
6	0002BH	H or L	
7	00033H	H or L	SIO0
8	0003BH	H or L	SIO1
9	00043H	H or L	ADC
10	0004BH	H or L	Port0/T4/T5

- Priority Level: X>H>L
- For equal priority levels, vector with lowest address takes precedence.
- ■Subroutine Stack Levels: 1024 levels maximum (Stack is located in RAM.)
- ■High-speed Multiplication/Division Instructions
 - 16 bits × 8 bits
 24 bits × 16 bits
 16 bits ÷ 8 bits
 24 bits ÷ 16 bits
 24 bits ÷ 16 bits
 16 tCYC execution time)
 25 tCYC execution time
 26 tCYC execution time
 27 tCYC execution time
 28 tCYC execution time
 29 tcYC execution time
 21 tCYC execution time

■Oscillation Circuits

- On-chip RC oscillation circuit for system clock use.
- On-chip CF oscillation circuit* for system clock use. (Rf built in)
- On-chip Crystal oscillation circuit* low speed system clock use. (Rf built in)
- Frequency variable RC oscillation circuit (internal) for system clock.
 - 1) Adjustable in ±4% (typ) step from a selected center frequency.
 - 2) Measures oscillation clock using a input signal from XT1 as a reference.
- * The CF oscillation terminal and the crystal oscillation terminal cannot be used at the same time because of commonness.

■System Clock Divider Function

• Able to reduce current consumption

Available minimum instruction cycle time: 300ns, 600ns, 1.2µs, 2.4µs, 4.8µs, 9.6µs, 19.2µs, 38.4µs, 76.8µs. (Using 10MHz main clock)

■Standby Function

• HALT mode

HALT mode is used to reduce power consumption. Program execution is stopped. Peripheral circuits still operate but VFD display and some serial transfer operations stop.

- 1) Oscillation circuits are not stopped automatically.
- 2) Release occurs on system reset or by interrupt.
- HOLD mode

HOLD mode is used to reduce power consumption. Both program execution and peripheral circuits are stopped.

- 1) The CF, RC, X'tal and frequency variable RC oscillators automatically stop operation.
- 2) Release occurs on any of the following conditions.
 - (1) input to the reset pin goes "Low"
 - (2) a specified level is input to at least one of INT0, INT1, INT2
 - (3) an interrupt condition arises at port 0
- X'tal HOLD mode.

X'tal HOLD mode is used to reduce power consumption. Program execution is stopped.

All peripheral circuits except the base-timer are stopped.

- 1) The CF, RC, frequency variable RC oscillation circuits stop automatically.
- 2) Crystal oscillator is maintained in its state at HOLD mode inception.
- 3) Release occurs on any of the following conditions.
 - (1) input to the reset pin goes "Low"
 - (2) Setting at least one of the INT0, INT1 and INT2 pins to the specified level
 - (3) Having an interrupt source established at port 0
 - (4) Having an interrupt source established in the base timer circuit
 - (5) Having an interrupt source established in the remote control receiver circuit

■On-chip Debugger

• Supports software debugging with the IC mounted on the target board.

■Package Form

• QFP80(14×14): Lead-free type

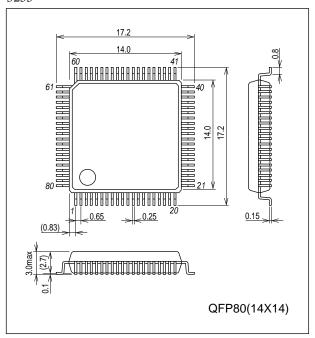
■Development Tools

• On-chip debugger: TCB87- type-B + LC87F6D64A

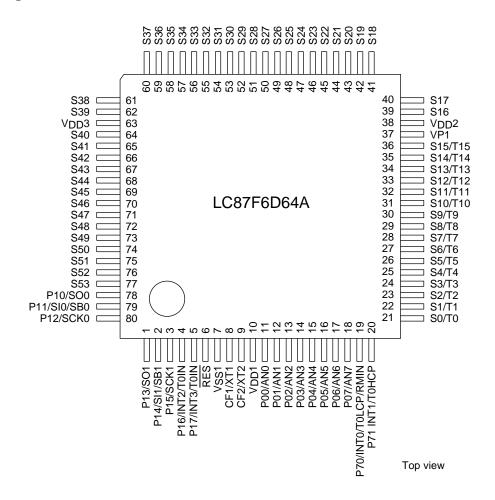
Package Dimensions

unit: mm (typ)

3255

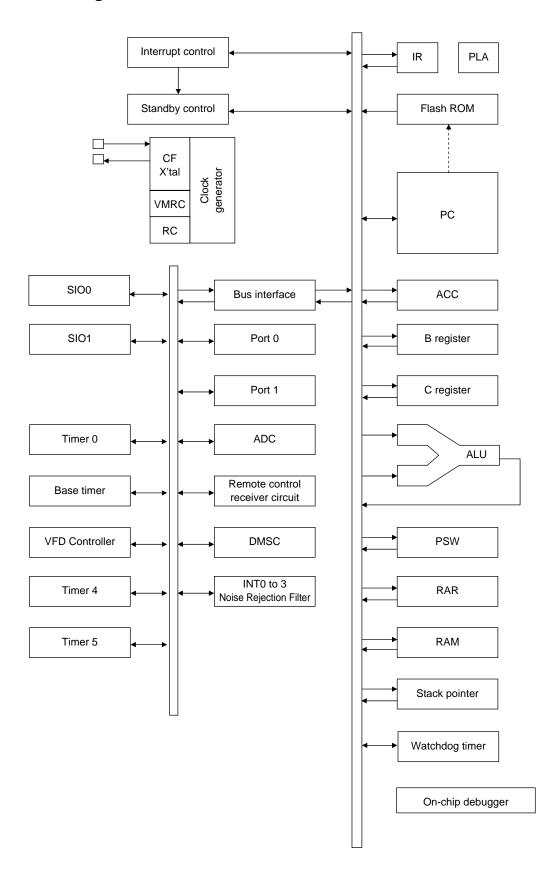


Pin Assignment



QFP80(14×14) "Lead-free Type"

System Block Diagram



Pin Description

Pin name	I/O				Function				Option
V _{SS} 1	-	Power supp	ly (-)						No
V _{DD} 1	-	Power supp	ly (+)						No
V _{DD} 2									
V _{DD} 3									
VP	-	VFD Power	supply (-)						No
PORT0	I/O	8bit input/out	itput port						Yes
P00 to P07		Data directi	on programma	able in nibble	units				
		Use of pull-	up resistor ca	n be specified	in nibble units				
		• Input for HC	LD release						
		Input for po	=						
		Other function							
					lected from sub	•			
PORT1	I/O			BGP0 to DBC	SP2 (P05 to P07)		+	Yes
_	1/0	8bit input/ou Data direction	-	able for each	hit				res
P10 to P17				able for each l n be specified					
		Other pin fu	=	ii be specilled	Tor each bit				
		P10: SIO0							
			data input/bus	input/output					
		P12: SIO0	clock input/ou	tput					
		P13: SIO1	data output						
		P14: SIO1	data input/bus	input/output					
			clock input/ou	tput					
		P16: INT2							
			Buzzer output						
		The following	types of inter	rupt detection	are possible:	1	1	i	
			Rising	Falling	Rising/ Falling	H level	L level		
		INT2	enable	enable	enable	disable	disable		
		INT3	enable	enable	enable	disable	disable		
DODTZ		Obit in a state		•		•		<u>'</u>	
PORT7		2bit input/ou Data direction		oified for each	h hit				
P70 to P71		Data direction	=	n be specified					
		Other functi	-	n be specified	Tor cach bit				
				lease input/Ti	mer 0L capture i	nput/			
			•	•	control receive	•			
		P71: INT1 ir	nput/HOLD re	lease input/Ti	mer 0H capture	input			
		The following	types of inter	rupt detection	are possible:			_	
			Rising	Falling	Rising/ Falling	H level	L level		
		INT0	enable	enable	disable	enable	enable		
		INT1	enable	enable	disable	enable	enable		
S0/T0 to S8/T8	0	• l arge curro		ı	ontroller digit (ca		1		No
S9/T9 to S15/T15	0	_	•		ontroller segmen		oogmont)	+	No
		_	•		-	livuigit		+	
S16 to S53	0		. ,	ontroller segm	ent				No
RES	I	Reset termina							No
CF1/XT1	I		illator selected						No
		Input termin							
		< crystal osci							
		Input for 32. When not in to	-						
CE2/XT2	0	vmen not in t <ceramic osc<="" p=""></ceramic>						+	No
CF2/XT2	U	ceramic oscOutput term							No
		 output terri crystal osci 							
		Output for 3			1				
			=		and leave open	circuit.			

Port Output Types

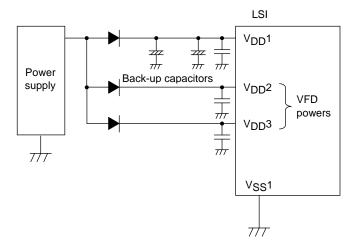
Output configuration and pull-up/pull-down resistor options are shown in the following table.

Input/output is possible even when port is set to output mode.

Terminal	Option Selected in Units of	Options	Output Format	Pull-up Resistor	Pull-down Resistor
P00 to P07	each bit	1	CMOS	Programmable	=
(Note 1)		2	Nch-open drain	Programmable	-
P10 to P17	each bit	1	CMOS	Programmable	-
		2	Nch-open drain	Programmable	-
P70	-	None	Nch-open drain	Programmable	-
P71	-	None	CMOS	Programmable	-
S0/T0 to S15/T15	-	None	High voltage Pch-open drain	-	Fixed
S16 to S53					

Note 1: Programmable pull-up resisters of Port 0 can be attached in nibble units (P00 to P03, P04 to P07).

 * Note: Connect as follows to reduce noise on $V_{\mbox{DD}}$ and increase the back-up time. $V_{\mbox{SS}1}$ must be connected together and grounded.



Absolute Maximum Ratings at Ta = 25°C, $V_{SS}1 = 0V$

	Dorometer	Cumbal	Din/Damarka	Conditions			Specifi	cation	
	Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Su	pply voltage	V _{DD} max	$V_{DD}1$, $V_{DD}2$, $V_{DD}3$	V _{DD} 1=V _{DD} 2=V _{DD} 3		-0.3		+6.5	
Inp	out voltage	V _I (1)	CF1/XT1, RES			-0.3		V _{DD} +0.3	
		V _I (2)	VP			V _{DD} -45		V _{DD} +0.3	
Οu	tput voltage	V _O (1)	S0/T0 to S15/T15 S16 to S53			V _{DD} -45		V _{DD} +0.3	V
		V _O (2)	CF2/XT2			-0.3		V _{DD} +0.3	
	out/Output tage	V _{IO} (1)	Ports 0, 1, 7			-0.3		V _{DD} +0.3	
	Peak output current	IOPH(1)	Ports 0, 1	CMOS output selected Current at each pin		-10			
		IOPH(2)	Port 71	Current at each pin		-5			
		IOPH(3)	S0/T0 to S15/T15	Current at each pin		-30			
		IOPH(4)	S16 to S53	Current at each pin		-15			
	Average output current	IOMH(1)	Ports 0, 1	CMOS output selected Current at each pin		-7.5			
		IOMH(2)	Port 71	Current at each pin		-3			
nt		IOMH(3)	S0/T0 to S15/T15	Current at each pin		-15			
urre		IOMH(4)	S16 to S53	Current at each pin		-10			
ont c	Total output	ΣΙΟΑΗ(1)	Port 0	Total of all pins		-30			
out	current	ΣΙΟΑΗ(2)	Port 1	Total of all pins		-30			
level		ΣΙΟΑΗ(3)	Ports 0, 1	Total of all pins		-30			
High level output current		ΣΙΟΑΗ(4)	Port 71	Total of all pins		-5			
_		ΣΙΟΑΗ(5)	S0/T0 to S15/T15	Total of all pins		-60			
		ΣΙΟΑΗ(6)	S16 to S33	Total of all pins		-60			mA
		ΣΙΟΑΗ(7)	S0/T0 to S15/T15 S16 to S33	Total of all pins		-60			
		ΣΙΟΑΗ(8)	S34 to S39	Total of all pins		-60			
		ΣΙΟΑΗ(9)	S40 to S47	Total of all pins		-60			
		ΣΙΟΑΗ(10)	S48 to S53	Total of all pins		-60			
		ΣΙΟΑΗ(11)	S34 to S53	Total of all pins		-60			
	Peak output	IOPL(1)	Ports 0, 1	Current at each pin				20	
ent	current	IOPL(2)	Port 7	Current at each pin				10	
curre	Total output	IPML(1)	Ports 0, 1	Current at each pin				15	
Low level output current	current	IOML(2)	Port 7	Current at each pin				7.5	
no le	Total output	ΣIOAL(1)	Port 0	Total of all pins				50	
leve	current	ΣIOAL(2)	Port 1	Total of all pins				50	
Low		ΣIOAL(3)	Port 7	Total of all pins				20	
		ΣIOAL(4)	Ports 0, 1, 7	Total of all pins				80	
	ximum power	Pd max	QFP80(14×14)	Ta=-40 to +85°C					mW
Op ter	erating nperature nge	Topr				-40		+85	
Sto	orage nperature nge	Tstg				-55		+125	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Allowable Operating Conditions at Ta = -40 °C to +85 °C, $V_{SS}1 = 0V$

_			2	<u> </u>		Specific	ation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Operating	V _{DD} (1)	V _{DD} 1=V _{DD} 2=V _{DD} 3	0.300μs≤tCYC≤200μs		3.0		5.5	
supply voltage range (Note 2-1)	V _{DD} (2)		0.735μs≤tCYC≤200μs		2.5		5.5	
Hold voltage	VHD	V _{DD} 1	RAM and the register data are kept in HOLD mode.		2.0		5.5	
Pull-down supply voltage	VP	VP			-35		V _{DD}	
Input high voltage	V _{IH} (1)	Ports 0, 1	Output disable	2.5 to 5.5	0.3V _{DD} +0.7		V _{DD}	
	V _{IH} (2)	Port 70 Watchdog timer	Output disable	2.5 to 5.5	0.9V _{DD}		V _{DD}	V
	V _{IH} (3)	XT1/CF1, RES		2.5 to 5.5	0.75V _{DD}		V_{DD}	
Input low voltage	V _{IL} (1)	Ports 0, 1 Port 71 Port 70 port input/interrupt	Output disable	2.5 to 5.5	V _{SS}		0.1V _{DD} +0.4	
	V _{IL} (2)	Port 70 Watchdog timer	Output disable	2.5 to 5.5	V _{SS}		0.8V _{DD} -1.0	
	V _{IL} (3)	XT1/CF1, RES		2.5 to 5.5	V _{SS}		0.25V _{DD}	
Operation	tCYC			3.0 to 5.5	0.300		200	
cycle time				2.5 to 5.5	0.735		200	μs
External	FEXCF(1)	CF1	CF2 open circuit	3.0 to 5.5	0.1		10	
system clock frequency			system clock divider set to 1/1external clock DUTY=50±5%	2.5 to 5.5	0.1		4	MHz
			CF2 open circuit	3.0 to 5.5	0.2		20	IVITZ
			 system clock divider set to 1/2 external clock DUTY=50±5% 	2.5 to 5.5	0.2		8	
Oscillation stabilizing time period	FmCF(1)	CF1, CF2	10MHz ceramic resonator oscillation Refer to figure 1	3.0 to 5.5		10		
(Note 2-2)	FmCF(2)	CF1, CF2	4MHz ceramic resonator oscillation Refer to figure 1	2.5 to 5.5		4		MHz
	FmRC		RC oscillation	2.5 to 5.5	0.3	1.0	2.0	
	FmVMRC		Frequency variable RC oscillation circuit	2.5 to 5.5		4		
	FsX'tal	XT1, XT2	32.768kHz crystal resonator oscillation Refer to figure 2	2.5 to 5.5		32.768		kHz

Note 2-1: Re-writeable on board V_{DD}≥4.5V.

Note 2-2: The oscillation constant is shown in table 1 and table 2.

The CF oscillation terminal and the crystal oscillation terminal cannot be used at the same time because of commonness.

Electrical Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = 0V$

Parameter	Symbol	Pin/Remarks	Conditions			Specifica	ation	
- diamotor	Cymbol	riii/rtomano	Containons	V _{DD} [V]	min	typ	max	unit
Input high current	I _{IH} (1)	Ports 0, 1, 7	Output disable Pull-up resister OFF. VIN=VDD (including OFF state leak current of the output Tr.)	2.5 to 5.5			1	
	I _{IH} (2)	RES	V _{IN} =V _{DD}	2.5 to 5.5			1	
	I _{IH} (3)	CF1/XT1	V _{IN} =V _{DD}	2.5 to 5.5			1	
Input low current	I _{IL} (1)	Ports 0, 1, 7	Output disable Pull-up resister OFF. VIN=VSS (including OFF state leak current of the output Tr.)	2.5 to 5.5	-1			μΑ
	I _{IL} (2)	RES	V _{IN} =V _{SS}	2.5 to 5.5	-1			
	I _{IL} (3)	CF1/XT1	V _{IN} =V _{SS}	2.5 to 5.5	-1			
Output high	V _{OH} (1)	Port 0: CMOS	I _{OH} =-1.0mA	4.5 to 5.5	V _{DD} -1			
voltage	V _{OH} (2)	output option	I _{OH} =-0.5mA	3.0 to 5.5	V _{DD} -1			
	V _{OH} (3)	Ports 1	I _{OH} =-0.1mA	2.5 to 5.5	V _{DD} -0.5			
	V _{OH} (4)	Port 71	I _{OH} =-0.4mA	2.5 to 5.5	V _{DD} -1			
	V _{OH} (5)	S0/T0 to S15/T15	I _{OH} =-20.0mA	4.5 to 5.5	V _{DD} -1.8			
	V _{OH} (6)	1	I _{OH} =-10.0mA	3.0 to 5.5	V _{DD} -1.8			
	V _{OH} (7)		IOH=-1.0mA IOH at any single pin is not over 1mA.	2.5 to 5.5	V _{DD} -1			
	V _{OH} (8)	S16 to S53	I _{OH} =-5.0mA	4.5 to 5.5	V _{DD} -1.8			V
	V _{OH} (9)	1	I _{OH} =-2.5mA	3.0 to 5.5	V _{DD} -1.8			
	V _{OH} (10)		I _{OH} =-1.0mA I _{OH} at any single pin is not over 1mA.	2.5 to 5.5	V _{DD} -1			
Output low	V _{OL} (1)	Ports 0, 1	I _{OL} =10mA	4.5 to 5.5			1.5	
voltage	V _{OL} (2)		I _{OL} =5mA	3.0 to 5.5			1.5	
	V _{OL} (3)		I _{OL} =1.6mA	2.5 to 5.5			0.4	
	V _{OL} (4)	Port 7	I _{OL} =1mA	2.5 to 5.5			0.4	
Pull-up resistor	Rpu	Ports 0, 1, 7	V _{OH} =0.9V _{DD}	4.5 to 5.5	15	40	70	
				2.5 to 4.5	25	70	150	kΩ
Output off-leak current	IOFF(1)	S0/T0 to S15/T15, S16 to S53	Output P-ch Tr. OFF VOUT=VSS	2.5 to 5.5	-1			
	IOFF(2)		Output P-ch Tr. OFF VOUT=VDD-40V	2.5 to 5.5	-30			μА
Pull-down resistor	Rpd	• S0/T0 to S15/T15 • S16 to S53	Output P-ch Tr. OFF VOUT=3V Vp=-30V	5.0	60	100	200	kΩ
Hysteresis voltage	VHYS(1)	• Ports 0, 1, 7 • RES		2.5 to 5.5		0.1V _{DD}		V
Pin capacitance	СР	All pins	f=1MHz All other terminals connected to V _{SS} . Ta=25°C	2.5 to 5.5		10		pF

Serial I/O Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = 0V$

1. SIO0 Serial I/O Characteristics (Note 4-1-1)

	_	Parameter	Symbol	Pin/	Conditions			Spec	ification	
		arameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
		Frequency	tSCK(1)	SCK0(P12)	See Fig. 6.		2			
	¥	Low level pulse width	tSCKL(1)				1			
	Input clock	High level pulse width	tSCKH(1)			2.5 to 5.5	1			
clock		tSCKHA(1)			4			tCYC		
Serial clock		Frequency	tSCK(2)	SCK0(P12)	CMOS output selected See Fig. 6.		4/3			
	ock	Low level pulse width	tSCKL(2)					1/2		1001
	bulse width High level pulse width	tSCKH(2)			2.5 to 5.5		1/2		tSCK	
	Outp		tSCKHA(2)		Continuous data transmission/reception mode CMOS output selected See Fig. 6.		tSCKH(2) +2tCYC		tSCKH(2) +(10/3) tCYC	tCYC
Serial input	Da	ta setup time	tsDI(1)	SB0(P11), SI0(P11)	Must be specified with respect to rising edge of SIOCLK. See Fig. 6.	2.5 to 5.5	0.03			
Serial	Da	ta hold time	thDI(1)			2.5 to 5.5	0.03			
	clock	Output delay time	tdD0(1)	SO0(P10), SB0(P11)	Continuous data transmission/reception mode (Note 4-1-3)	2.5 to 5.5			(1/3)tCYC +0.05	
output	Serial output Output clock Input clock		tdD0(2)		Synchronous 8-bit mode (Note 4-1-3)	2.5 to 5.5			1tCYC +0.05	μs
Serial			tdD0(3)		(Note 4-1-3)	2.5 to 5.5			(1/3)tCYC +0.05	

Note 4-1-1: These specifications are theoretical values. Add margin depending on its use.

Note 4-1-2: To use serial-clock-input in continuous trans/rec mode, a time from SI0RUN being set when serial clock is "H" to the first negative edge of the serial clock must be longer than tSCKHA.

Note 4-1-3: Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 6.

2. SIO1 Serial I/O Characteristics (Note 4-2-1)

		Daramatar	Cumbal	Pin/	Conditions			Speci	fication	
	ŀ	Parameter	Symbol	Remarks	Conditions	$V_{DD}[V]$	min	typ	max	unit
		Frequency	tSCK(3)	SCK1(P15)	See Fig. 6.		2			
	Š			<u> </u>						
	Input clock	Low level	tSCKL(3)			2.5 to 5.5	1			
	Inpu	pulse width	1001(11(0)	1		-				tCYC
Sock		High level pulse width	tSCKH(3)				1			
Serial clock		Frequency	tSCK(4)	SCK1(P15)	CMOS output selected					
Se	충		,		• See Fig. 6.		2			
	Output clock	Low level	tSCKL(4)			2.5 to 5.5		1/2		
	utbu	pulse width				2.3 10 3.3		1/2		tSCK
	Ō	High level	tSCKH(4)					1/2		took
		pulse width					1		1	
	Da	ta setup time	tsDI(2)	SB1(P14),	Must be specified with	054.55	0.00			
Serial input				SI1(P14)	respect to rising edge of SIOCLK.	2.5 to 5.5	0.03			
rial	Da	ta hold time	thDI(2)	-	• See Fig. 6.					
Se			(_)		3 -	2.5 to 5.5	0.03			
	Οι	tput delay time	tdD0(4)	SO1(P13),	Must be specified with					μs
Ļ				SB1(P14)	respect to falling edge of					,
nd _{tr}					SIOCLK.				(4 (8) (8) (8	
Serial output					Must be specified as the	2.5 to 5.5			(1/3)tCYC	
Seris					time to the beginning of output state change in				+0.05	
0,					open drain output mode.					
					• See Fig. 6.					

Note 4-2-1: These specifications are theoretical values. Add margin depending on its use.

Pulse Input Conditions at Ta = -40°C to +85°C, VSS1 = 0V

	0	D'. (D	0 - 171			Specif	fication	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
High/low level	tPIH(1)	INT0(P70),	Interrupt acceptable					
pulse width	tPIL(1)	INT1(P71),	• Events to timer 0, 1 can be input.	2.5 to 5.5	1			
		INT2(P16)						
	tPIH(2)	INT3(P17)	Interrupt acceptable					
	tPIL(2)	(Noise rejection ratio	Events to timer 0 can be input.	2.5 to 5.5	2			
		set to 1/1.)						tCYC
	tPIH(3)	INT3(P17)	Interrupt acceptable					ICYC
	tPIL(3)	(Noise rejection ratio	Events to timer 0 can be input.	2.5 to 5.5	64			
		set to 1/32.)						
	tPIH(4)	INT3(P17)	Interrupt acceptable					
	tPIL(4)	(Noise rejection ratio	Events to timer 0 can be input.	2.5 to 5.5	256			
		set to 1/128.)						
	tPIL(5)	RES	Reset possible	2.5 to 5.5	200			μs

AD Converter Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = 0V$

Doromotor	Cumbal	Din/Domorles	Conditions			Specifi	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Resolution	N	AN0(P00) to		3.0 to 5.5		8		bit
Absolute precision	ET	AN7(P07)	(Note 6-1)	3.0 to 5.5			±1.5	LSB
Conversion time	tCAD		AD conversion time=32×tCYC (ADCR2=0) (Note 6-2)	4.5 to 5.5	15.62 (tCYC= 0.488μs)		97.92 (tCYC= 3.06μs)	
				3.0 to 5.5	23.52 (tCYC= 0.735μs)		97.92 (tCYC= 3.06μs)	
			AD conversion time=64×tCYC (ADCR2=1) (Note 6-2)	4.5 to 5.5	18.82 (tCYC= 0.294μs)		97.92 (tCYC= 1.53μs)	μs
				3.0 to 5.5	47.04 (tCYC= 0.735μs)		97.92 (tCYC= 1.53μs)	
Analog input voltage range	VAIN			3.0 to 5.5	V _{SS}		V _{DD}	٧
Analog port	IAINH		VAIN=V _{DD}	3.0 to 5.5			1	
input current	IAINL		VAIN=V _{SS}	3.0 to 5.5	-1	·		μΑ

Note 6-1: Absolute precision not including quantizing error ($\pm 1/2$ LSB).

Note 6-2: Conversion time means time from executing AD conversion instruction to loading complete digital value to register.

Consumption Current Characteristics at Ta = -40°C to +85°C, $V_{SS}1 = 0V$

D	O. make al	Pin/	O an distance			Specif	ication			
Parameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit		
Current dissipation during basic	IDDOP(1)	V _{DD} 1 =V _{DD} 2 =V _{DD} 3	FmCF=10Hz for ceramic resonator oscillation System clock: 10MHz	4.5 to 5.5		8.0	24			
operation (Note 7-1)			Internal RC oscillation stopped. 1/1 frequency division ratio	3.0 to 4.5		6.1	19			
		CF1=15MHz for external clock System clock: CF1 oscillation	4.5 to 5.5		10.5	32				
		Internal RC oscillation stopped.1/2 frequency division ratio	3.0 to 4.5		9.5	28	mA			
	IDDOP(3)		FmCF=4MHz for ceramic resonator oscillation	4.5 to 5.5		3.8	9.5			
			System clock: 4MHz Internal RC oscillation stopped. 1/1 frequency division ratio	3.0 to 4.5		3.1	7.8			
	IDDOP(4)		• FmCF=0Hz (No oscillation)	4.5 to 5.5		0.72	3			
_					System clock: RC oscillationDivider set to 1/2	2.5 to 4.5		0.53	2	
	IDDOP(5)		FsX'tal=32.768kHz for crystal oscillation System clock: 32.768KHz	4.5 to 5.5		39	220			
			Internal RC oscillation stopped. 1/2 frequency division ratio	2.5 to 4.5		25	150	μА		

Note 7-1: The currents of the output transistors and the pull-up MOS transistors are ignored.

Continued on next page.

Continued from preceding page.

Parameter	Symbol	Pin/	Conditions			Specif	ication	
Parameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Current dissipation HALT mode	IDDHALT(1)	V _{DD} 1 =V _{DD} 2 =V _{DD} 3	HALT mode • FmCF=10MHz for Ceramic resonator oscillation	4.5 to 5.5		3.0	9	
(Note 7-1)			System clock : 10MHz Internal RC oscillation stopped. Divider: 1/1	3.0 to 4.5		2.1	6.3	
	IDDHALT(2)		HALT mode • CF1=15MHz for external clock • System clock : CF1 oscillation	4.5 to 5.5		4.2	12.5	mA
			Internal RC oscillation stopped. Divider 1/2	3.0 to 4.5		2.5	7.8	IIIA
	IDDHALT(3)		HALT mode • FmCF=4MHz for Ceramic resonator oscillation	4.5 to 5.5		1.4	3.5	
			System clock : 4MHz Internal RC oscillation stopped. Divider: 1/1	2.5 to 4.5		1.0	2.5	
	IDDHALT(4)		HALT mode • FmCF=0Hz (When oscillation stops.)	4.5 to 5.5		420	1600	
			System clock : RC oscillation Divider: 1/2	2.5 to 4.5		280	1100	
	IDDHALT(5)		HALT mode • FsX'tal=32.768kHz for crystal oscillation	4.5 to 5.5		24	80	
			Internal RC oscillation stopped.System clock : 32.768kHzDivider: 1/2	2.5 to 4.5		14	60	μΑ
Current	IDDHOLD(1)	V _{DD} 1	HOLD mode	4.5 to 5.5		0.10	20	
dissipation HOLD mode			CF1=V _{DD} or open circuit (when using external clock)	2.5 to 4.5		0.02	15	
Current dissipation	IDDHOLD(2)	V _{DD} 1	Date/time clock HOLD mode • CF1=V _{DD} or open circuit	4.5 to 5.5		21	65	
Date/time clock HOLD mode			(when using external clock) • FsX'tal=32.768kHz for crystal oscillation	2.5 to 4.5		11	50	

Note 7-1: The currents of the output transistors and the pull-up MOS transistors are ignored.

F-ROM Programming Characteristics at Ta = +10°C to +55°C, $V_SS1 = 0V$

D	O. male al	Pin/	Condition -		Specification				
Parameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit	
On-board writing current	IDDFW(1)	V _{DD} 1	The current dissipation of the microcomputer is excluded.	4.5 to 5.5		5	10	mA	
Writing time	tFW(1)		Erase time	4		20	30	ms	
	tFW(2)		Writing time	4.5 to 5.5		40	60	μs	

Characteristics of a Sample Main System Clock Oscillation Circuit

The characteristics in the table bellow is based on the following conditions:

- 1. Use the standard evaluation board Our company has provided.
- 2. Use the peripheral parts with indicated value externally.
- 3. The peripheral parts value is a recommended value of oscillator manufacturer.

Table 1 Characteristics of a Sample Main System Clock Oscillator Circuit with a Ceramic Oscillator

Frequency Manufacture	Mary ford	0	Circ	uit Parame	eters	Operating Supply	Oscillation Stabilizing Time		
	Manufacturer	Oscillator	C1	C2	Rd1	Voltage Range	typ	max	Notes
			[pF]	[pF]	[Ω]	[V]	[ms]	[ms]	
10MHz MURATA	MUDATA	CSTCE10M0G52-R0	10	10	1k	2.8 to 5.5	0.029		
	CSTLS10M0G53-B0	15	15	1k	3.0 to 5.5	0.028			
4MHz MURATA	MUDATA	CSTCR4M00G53-R0	15	15	2.2k	2.3 to 5.5	0.034		
	MURATA	CSTLS4M00G53-B0	15	15	2.2k	2.3 to 5.5	0.030		

The oscillation stabilizing time is a period until the oscillation becomes stable after V_{DD} becomes higher than minimum operating voltage. (Refer to Figure 4)

Characteristics of a Sample Subsystem Clock Oscillator Circuit

The characteristics in the table bellow is based on the following conditions:

- 1. Use the standard evaluation board Our company has provided.
- 2. Use the peripheral parts with indicated value externally.
- 3. The peripheral parts value is a recommended value of oscillator manufacturer

Table 2 Characteristics of a Sample Subsystem Clock Oscillator Circuit with a Crystal Oscillator

Frequency M	Manufacturar	Oscillator	Circuit Parameters				Operating Supply Voltage	Oscillation Stabilizing Time		Neter
	Manufacturer		С3	C4	Rf	Rd2	Range	typ	max	Notes
			[pF]	[pF]	$[\Omega]$	[Ω]	[V]	[s]	[s]	

The oscillation stabilizing time is a period until the oscillation becomes stable after executing the instruction which starts the sub-clock oscillation or after releasing the HOLD mode. (Refer to Figure 4)

Notes: Since the circuit pattern affects the oscillation frequency, place the oscillation-related parts as close to the oscillation pins as possible with the shortest possible pattern length.

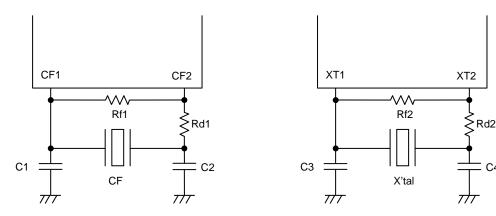
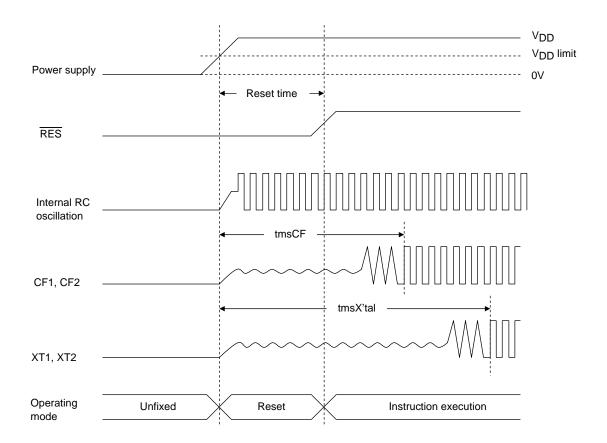


Figure 1 Ceramic Oscillation Circuit

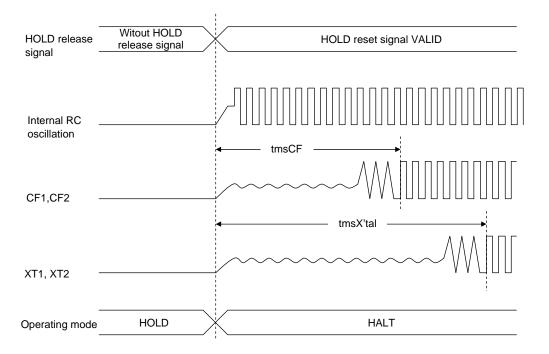
Figure 2 Crystal Oscillation Circuit



Figure 3 AC Timing Measurement Point

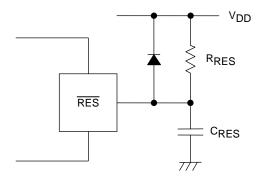


Reset Time and Oscillation Stabilization Time



HOLD Reset Signal and Oscillation Stabilization Time

Figure 4 Oscillation Stabilization Time



Note:

Set CRES, RRES values such that reset time exceeds $200\mu s$.

Figure 5 Reset Circuit

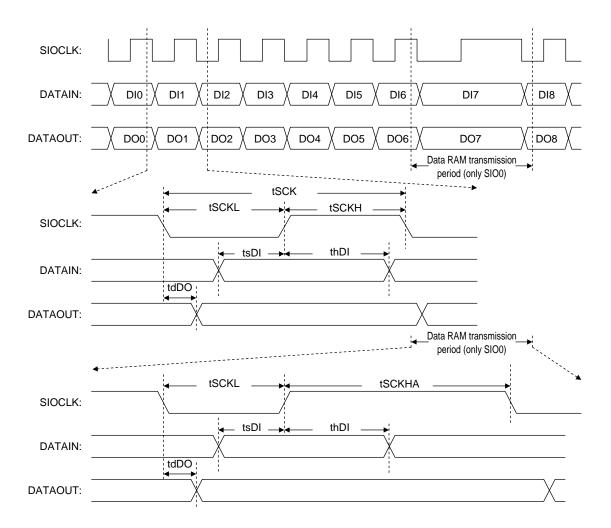


Figure 6 Serial I/O Waveform

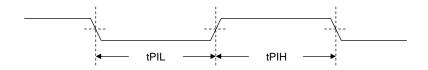


Figure 7 Pulse Input Timing Signal Waveform

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